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A dense NASICON sheet prepared by tape-casting and low temperature sintering

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PII: S0013-4686(18)31024-7

DOI: [10.1016/j.electacta.2018.05.020](https://doi.org/10.1016/j.electacta.2018.05.020)

Reference: EA 31806

To appear in: *Electrochimica Acta*

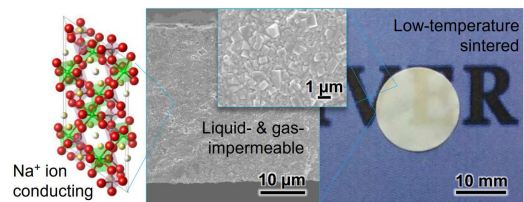
Received Date: 12 February 2018

Revised Date: 30 April 2018

Accepted Date: 2 May 2018

Please cite this article as: K. Okubo, H. Wang, K. Hayashi, M. Inada, N. Enomoto, G. Hasegawa, T. Osawa, H. Takamura, A dense NASICON sheet prepared by tape-casting and low temperature sintering, *Electrochimica Acta* (2018), doi: 10.1016/j.electacta.2018.05.020.

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